USHIO Applying Light to Life



Data Sheet

2024.11

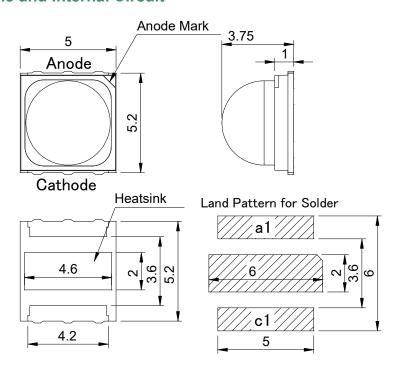
PRELIMINARY

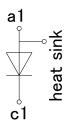
epitex

SMBB1070D-1100-05

1070nm High Power TOP LED

Outline and Internal Circuit





(Unit: mm)

Features

• Chip Material : InGaAsP

• Chip Dimension: 1mm * 1mm

• Number of Chips : 1pce

• Peak Wavelength: 1070nm typ.

• Lead Frame Die : Silver Plated on Copper

• Package Resin : Polyamide Resin

• Lens : Silicone Resin

Application

Absolute Maximum Ratings (Tc=25°C)

Item	Symbol	Ratings	Unit
Power Dissipation	PD	4200	mW
Forward Current	lF	1500	mA
Pulse Forward Current	IFP	4000	mA
Reverse Voltage	VR	5	V
Thermal Resistance	Rthjs	10	K/W
Junction Temperature	Tj	120	°C
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +100	°C

‡Pulse Forward Current condition : Duty 1% and Pulse Width=10us.

‡Soldering condition : Refer to technical support information on the website.

Optical and Electrical Characteristics (Tc=25°C)

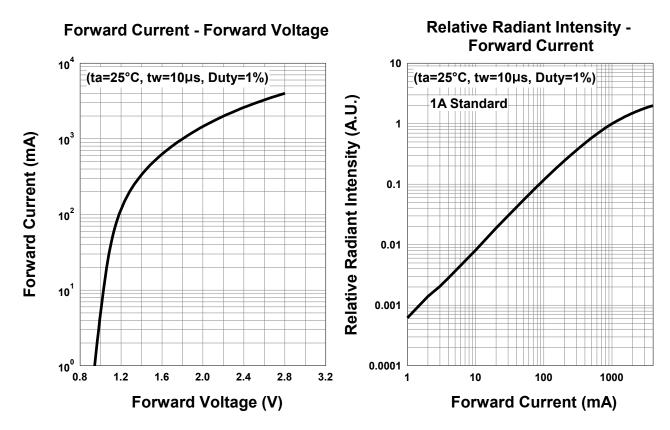
(*: 100% testing, **: reference value)

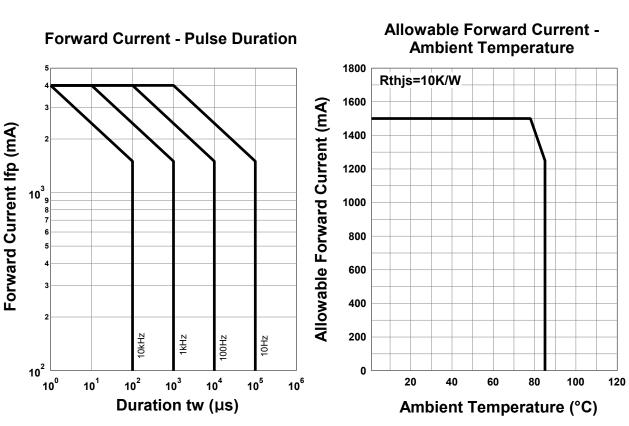
NF 1.8 (2.2) I	Condition
VF	
Compared Voltage	==1A*
VFP 2.5 IF 2.8 IF 2.8 IF Reverse Current IR 10 uA V 130 260 IF (140) 280 IF Total Radiated Power PO 490 mW IF 650 IF 210 II	=1.5A**
2.8 IF Reverse Current IR	P=2A**
Reverse Current IR	P=3A**
130 260	P=4A**
Total Radiated Power	R=5V*
Total Radiated Power PO 490 mW IF 580 IF 650 IF 210	==1A*
580 IF 650 IF	=1.5A**
650 IF	P=2A**
210 II	P=3A**
	P=4A**
230 IF	=1A**
	=1.5A**
Radiant Intensity IE 410 mW/sr IF	P=2A**
480 IF	P=3A**
530 IF	P=4A**
Peak Wavelength λp 1020 1120 nm I	==1A*
Half Width Δλ 50 nm II	=1A**
Viewing Half Angle θ 1/2 \pm 45 deg. IF=	100mA**
Rise Time tr 90 ns II	=1A**
Fall Time tf 30 ns II	=1A**

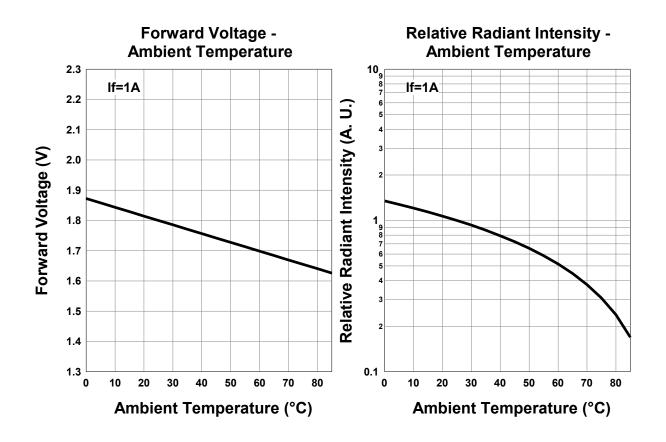
[‡] Radiated Power is measured by G8370-85.

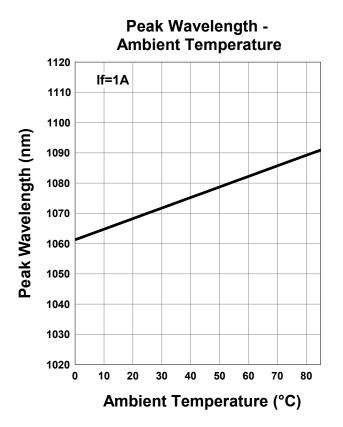
[‡] Radiant Intensity is measured by Ando Optical Multi Meter AQ2140 & AQ2742.

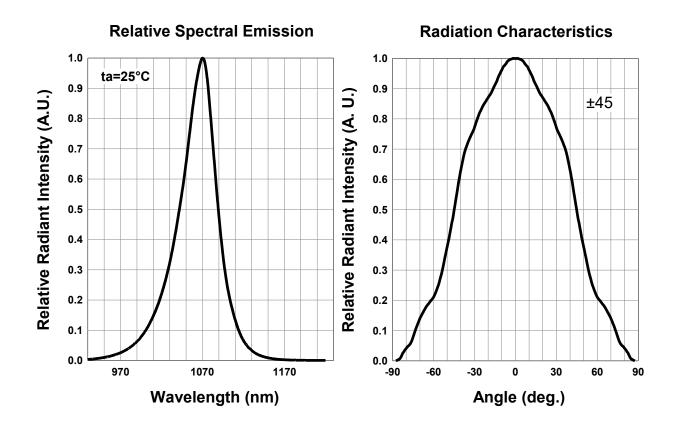
Typical Characteristic Curves



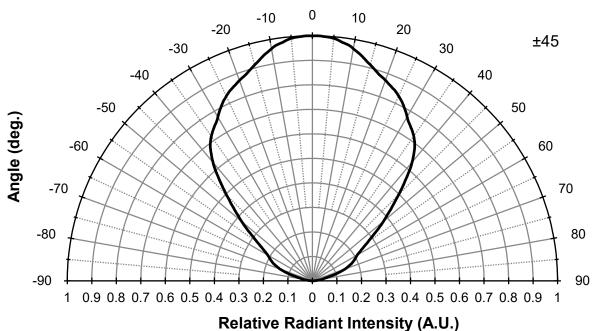












Wrapping

Moisture barrier bag aluminum laminated film with a desiccant to keep out the moisture absorption during the transportation and storage.

SMD LED storage and handling precautions Storage Conditions before Opening a Moisture-Barrier Aluminum Bag

- Before opening a moisture-barrier aluminum bag, please store it at <30°C, <60%RH.
- Please note that the maximum shelf life is 12 months under these conditions.

Storage Conditions after Opening a Moisture-Barrier Aluminum Bag

- After opening a moisture-barrier aluminum bag, store the aluminum bag and silica gel in a desiccator.
- After opening the bag, please solder the LEDs within 72 hours in a room with 5 30°C, <50%RH.
- Please put any unused, remaining LEDs and silica gel back in the same aluminum bag and then vacuum-seal the bag.
- It is recommended to keep the re-sealed bag in a desiccator at <30%RH.
- The 72-hour- long floor life does not include the time while LEDs are stored in the moisture-barrier aluminum bag. However, we strongly recommend to solder the LEDs as soon as possible after opening the aluminum bag.

Notes about Re-sealing a Moisture-Barrier Aluminum Bag

When vacuum-sealing an opened aluminum bag, if you find the moisture-indicator of the silica gel
has changed to pink from blue (indicating a relative humidity of 30 % or more), please do not use
the unused LEDs, the aluminum bag, or the silica gel.

Notes about Opening a Re-sealed Moisture-Barrier Aluminum Bag

 When opening a vacuumed and re-sealed aluminum bag in order to use the remaining LEDs stored in the bag, if you find that the moisture-indicator of the silica has changed to pink, please do not use the LEDs.

Disclaimer

Product specifications and data shown in this product catalog are subject to change without notice for the purposes of improving product performance, reliability, design, or otherwise.

Product data and parameters in this catalog are typical values based on reasonably up-to-date measurements. Product data and parameters may vary by user application and over time.

Products shown in this catalog are intended to be used for general electronic equipment. Products are not guaranteed for applications where product malfunction or failure may cause personal injury or death, including but not limited to life-supporting / saving devices, medical devices, safety devices, airplanes, aerospace equipment, automobiles, traffic control systems, and nuclear reactor control systems.

Technical Support Information

https://www.ushio.co.jp/en/led/technology/index.html



